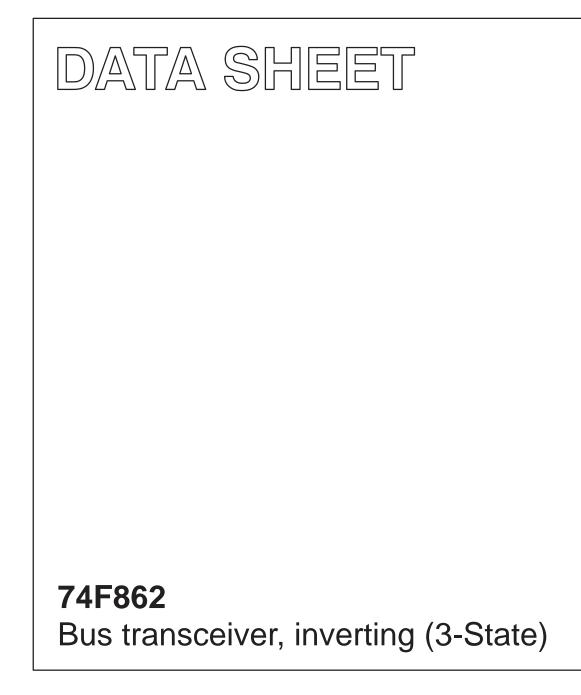
INTEGRATED CIRCUITS



Product data Replaces data sheet 74F862, 74F863 of 2000 Mar 24 2004 Jan 23



Philips Semiconductors

74F862

FEATURES

- Provide high performance bus interface buffering for wide data/address paths or buses carrying parity
- \bullet High impedance NPN base inputs for reduced loading (20 μA in HIGH and LOW states)
- I_{IL} is 20 μ A for minimum bus loading
- Buffered control inputs for light loading, or increased fan-in as required with MOS microprocessors
- · Positive and negative over-shoots are clamped to ground
- 3-State outputs glitch free during power-up and power-down
- Slim dual In-line (DIP) 300 mil package
- Broadside pinout
- Outputs sink 64 mA

ORDERING INFORMATION

COMMERCIAL RANGE: V_{CC} = 5 V ± 10%; T_{amb} = 0 °C to +70 °C

DESCRIPTION

The 74F862 bus transceiver provides a high performance inverting bus interface for wide data/address paths of buses carrying parity.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F862	6.0 ns	150 mA

Type number	Package	ackage				
	Name	lame Description				
N74F862N	DIP24	plastic dual in-line package; 24 leads (300 mil)	SOT222-1			
N74F862D (see Note 1)	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1			

NOTE:

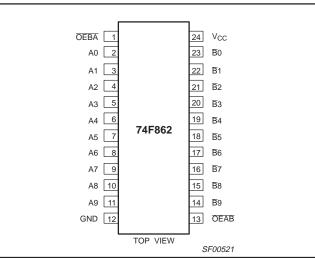
1. Thermal mounting techniques are recommended. See SMD Process Applications for a discussion of thermal considerations for surface mounted devices.

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0 – A9	Data transmit inputs	1.0/0.033	20 μΑ / 20 μΑ
$\overline{B}0 - \overline{B}9$	Data receive inputs	1.0/0.033	20 μΑ / 20 μΑ
OEBA	OEBA Transmit output enable input		20 μΑ / 20 μΑ
OEAB	Receive output enable input	1.0/0.033	20 μΑ / 20 μΑ

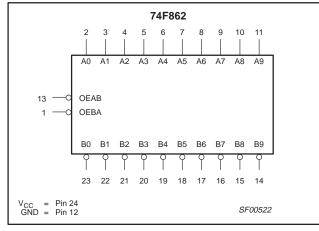
NOTE: One (1.0) FAST Unit Load is defined as: $20 \ \mu$ A in the HiGH state and 0.6 mA in the LOW state.

PIN CONFIGURATION

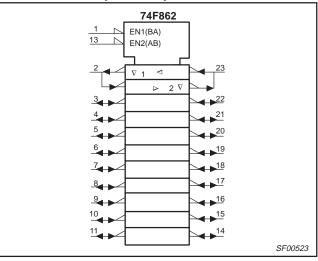


74F862

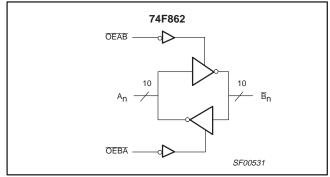
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

INP	UTS	OPERATING MODES
OEAB	OEBA	OPERATING MODES
L	Н	A data to B bus, inverted
Н	L	B bus to A data, inverted
Н	Н	Z

H = HIGH voltage level L = LOW voltage level

Z = High impedance "off" state

74F862

ABSOLUTE MAXIMUM RATINGS

Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +5.5	V
I _{OUT}	Current applied to output in LOW output state	128	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
STWIDOL	PARAMETER	MIN	NOM	МАХ	UNIT
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	HIGH-level input voltage	2.0	-	-	V
V _{IL}	LOW-level input voltage	-	-	0.8	V
I _{IK}	Input clamp current	-	-	-18	mA
I _{OH}	HIGH-level output current	-	-	-24	mA
I _{OL}	LOW-level output current	-	-	64	mA
T _{amb}	Operating free-air temperature range	0	-	70	°C

Product data

DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range unless otherwise noted.

			TEST CONDITIONS ¹			LIMITS			
SYMBOL	PARAMETER	MIN				TYP ²	MAX		
			$V_{CC} = MIN,$ $V_{IL} = MAX,$ $I_{OH} = -1 mA$	± 10% V _{CC}	2.4	-	-	V	
M					\pm 5% V _{CC}	2.4	3.3	-	V
V _{OH}	HIGH-level output voltage		$V_{CC} = MIN,$ $V_{IL} = MAX,$	1 24 mA	\pm 10% V _{CC}	2.0	-	-	V
		$V_{IH} = MIN$	I _{OH} = -24 mA	\pm 5% V _{CC}	2.0	-	-	V	
M			$V_{CC} = MIN,$ $V_{IL} = MAX,$	I _{OL} = 48 mA	\pm 10% V _{CC}	-	0.38	0.55	V
V _{OL}	LOW-level output voltage		$V_{IH} = MIN$	I _{OL} = 64 mA	\pm 5% V _{CC}	-	0.42	0.55	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$			-	-0.73	-1.2	V	
	Input current at maximum OEAB, OEBA		$V_{CC} = 0.0 \text{ V}, \text{ V}_{I} = 7.0 \text{ V}$			-	-	100	μΑ
łı	input voltage	A_n, \overline{B}_n	$V_{CC} = 5.5 \text{ V}, \text{ V}_{I} = 5.5 \text{ V}$			-	-	1	mA
I _{IH}	HIGH-level input current		$V_{CC} = MAX, V_I = 2.7 V$		-	-	20	μΑ	
Ι _{ΙL}	LOW-level input current		$V_{CC} = MAX, V_I = 0.5 V$		-	-	-20	μΑ	
I _{IH} + I _{OZH}	Off-state output current HIGH-level voltage applied		V _{CC} = MAX, V _O = 2.7 V		-	-	70	μA	
I _{IL} + I _{OZL}	Off-state output current LOW-level voltage applied		V _{CC} = MAX,	V _O = 0.5 V		-	-	-70	μA
I _{OS}	Short-circuit output current ³	-	V _{CC} = MAX		-100	-	-225	mA	
		I _{CCH}				-	90	130	mA
I _{CC}	Supply current total	I _{CCL}	V _{CC} = MAX			-	120	170	mA
		I _{CCZ}				-	130	160	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

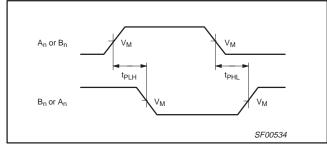
2. All typical values are at $V_{CC} = 5 \text{ V}$, $T_{amb} = 25 \text{ °C}$. 3. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

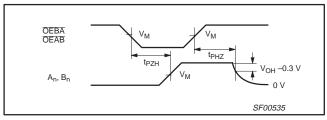
					LIMIT	S		
SYMBOL	PARAMETER	TEST CONDITION		_{mb} = +25 V _{CC} = 5 V 0 pF; R _L =		T _{amb} = 0 °C V _{CC} = 5 C _L = 50 pF;	C to +70 °C V ± 10% R _L = 500 Ω	UNIT
			MIN	ТҮР	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay A_n or \overline{B}_n	Waveform 1	4.0 1.5	6.0 3.5	9.0 6.5	3.0 1.5	10.0 7.0	ns
t _{PLH} t _{PHL}	Propagation delay \overline{B}_n or A_n	Waveform 1	4.0 1.5	6.0 3.5	9.0 6.5	3.5 1.5	10.0 7.0	ns
t _{PZH} t _{PZL}	Output Enable time HIGH or LOW level OEBA to A _n	Waveform 2 Waveform 3	6.5 6.0	8.5 7.5	12.0 12.0	5.5 5.0	13.5 14.0	ns
t _{PZH} t _{PZL}	Output Enable time HIGH or LOW level $\overline{\text{OEAB}}$ to $\overline{\text{B}}_{\text{n}}$	Waveform 2 Waveform 3	6.5 6.0	8.5 7.5	12.0 12.0	5.5 5.0	13.5 14.0	ns
t _{PHZ} t _{PLZ}	Output Disable time HIGH or LOW level OEBA to A _n	Waveform 2 Waveform 3	3.0 2.5	5.0 4.0	8.5 8.5	2.5 2.0	9.5 9.0	ns
t _{PHZ} t _{PLZ}	Output Disable time HIGH or LOW level $\overline{\text{OEAB}}$ to $\overline{\text{B}}_{\text{n}}$	Waveform 2 Waveform 3	3.0 2.5	5.0 4.0	8.5 8.5	2.5 2.0	9.5 9.0	ns

AC WAVEFORMS

For all waveforms, $V_M = 1.5$ V.

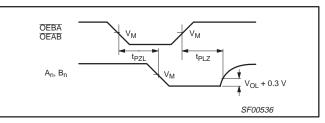


Waveform 1. Propagation delay for inverting output

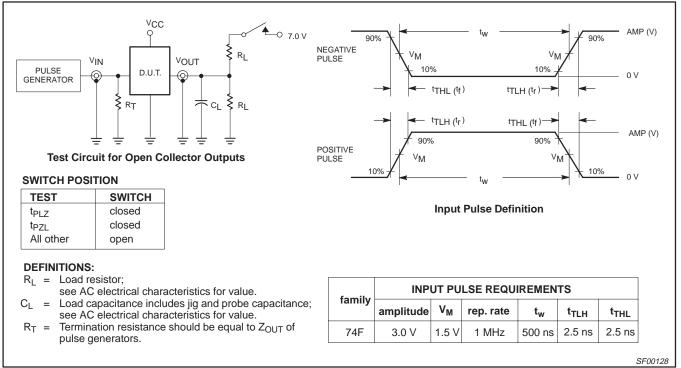


Waveform 2. 3-State Output Enable time to HIGH level and Output Disable time from HIGH level

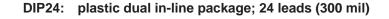
TEST CIRCUITS AND WAVEFORMS

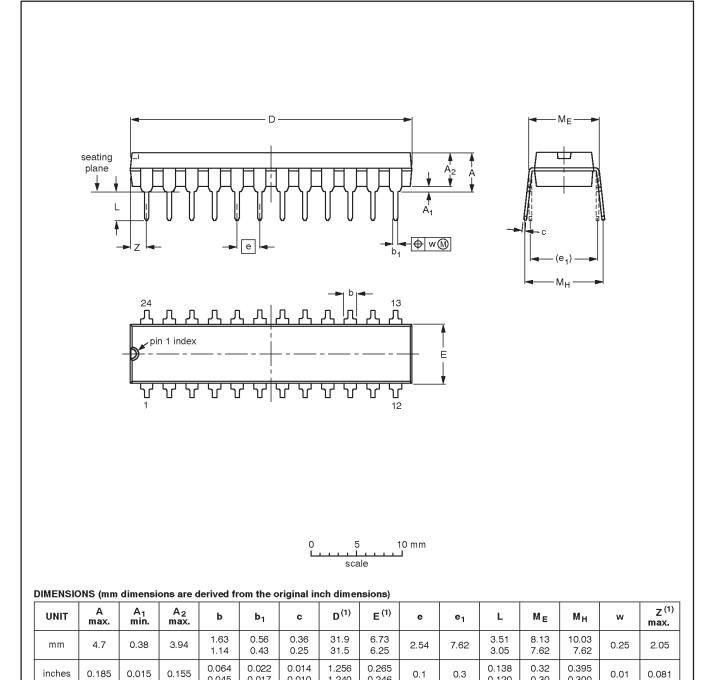


Waveform 3. 3-State Output Enable time to LOW level and Output Disable time from LOW level



74F862





Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

0.045

0.017

0.010

OUTLINE	JTLINE REFERENCES					ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	1350E DATE	
SOT222-1		MS-001				-99-12-27- 03-03-12	

1.240

0.246

0.120

0.30

0.300

SOT222-1

74F862

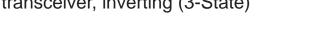
SOT137-1

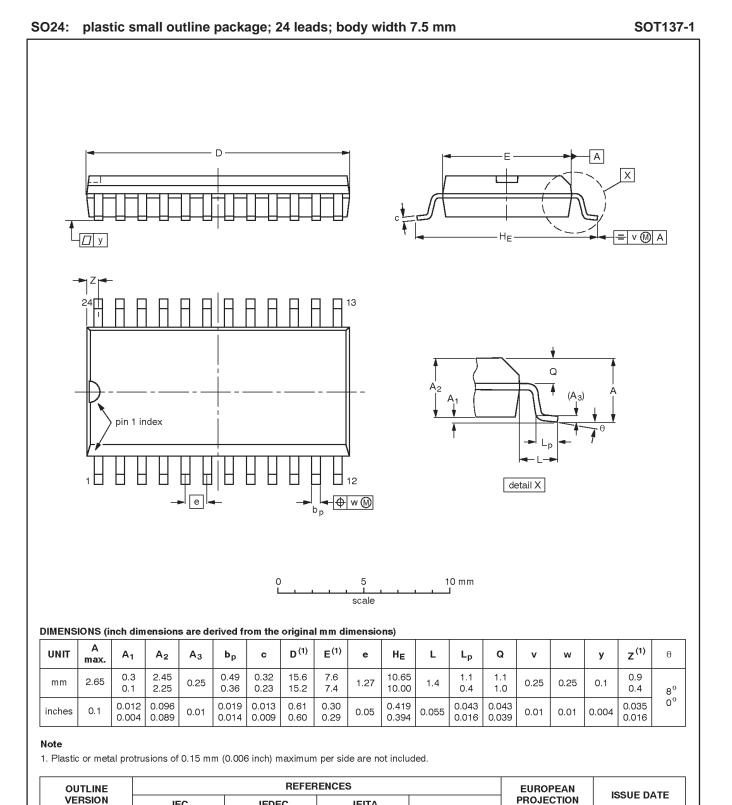
IEC

075E05

JEDEC

MS-013





74F862

99-12-27

03-02-19

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JEITA

REVISION HISTORY

Date

Bus transceiver, inverting (3-State)

Description

Rev

_5	20040123	Product data (9397 750 12749). ECN 853-0881 A15378 of 22 January 2004. Replaces Product specification 74F862_74F863_4 dated 2000 Mar 24 (9397 750 06999).
		Modifications:
		 Delete all references to 74F863 (product discontinued).
		 "Input and output loading and fan-out table" on page 2; for Pins A0 – A9 and B0 – B9: – change 74F(U.L.) HIGH/LOW from "3.5/0.117" to "1.0/0.033" – change Load value HIGH/LOW from "70 μA / 70 μA" to "20 μA / 20 μA"
		 "DC electrical characteristics" table on page 5; V_{OL} test condition, at ± 10% V_{CC}: change "I_{OL} = -48 mA" to "I_{OL} = 48 mA"
_4	20000324	Product specification (9397 750 06999). ECN 853-0881 23378 of 24 March 2000. Supersedes data of 1999 Jan 08.

Product data

74F862

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
111	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 01-04

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